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ENVIRONMENTAL PROTECTION AND  
MANAGEMENT ACT  
(CHAPTER 94A)

ENVIRONMENTAL PROTECTION AND  
MANAGEMENT ACT  
(AMENDMENT OF SECOND SCHEDULE)  
ORDER 2016

In exercise of the powers conferred by section 76(1) of the Environmental Protection and Management Act, the Minister for the Environment and Water Resources makes the following Order:

**Citation and commencement**

1. This Order is the Environmental Protection and Management Act (Amendment of Second Schedule) Order 2016 and comes into operation on 1 June 2017.

**Amendment of Part I of Second Schedule**

2. Part I of the Second Schedule to the Environmental Protection and Management Act is amended —

(a) by inserting, immediately below the substance “Bromine; Bromine solutions”, the following substance:

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Cadmium and its compounds in controlled EEE	Controlled EEE containing cadmium not exceeding 0.01% maximum concentration value by weight of homogeneous material in controlled EEE; Cadmium and its compounds in electrical contact; Cadmium in filter glass or glass used for reflectance standards; Cadmium in printing ink for the application of enamel on glass;
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	<p>Cadmium alloy as electrical or mechanical solder joint to electrical conductor located directly on voice coil in transducer used in high-powered loudspeaker with sound pressure level of 100 dB (A) or more;</p> <p>Cadmium and cadmium oxide in thick film paste used on aluminium bonded beryllium oxide.</p>
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(b) by inserting, immediately below the substance “Hexabromocyclododecane (HBCD)”, the following substance:

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<p>Hexavalent chromium in controlled EEE</p>	<p>Controlled EEE containing hexavalent chromium not exceeding 0.1% maximum concentration value by weight of homogeneous material in controlled EEE;</p> <p>Hexavalent chromium as anticorrosion agent, not exceeding 0.75% by weight, in the cooling solution of carbon steel cooling system in absorption refrigerator.</p>
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(c) by inserting, immediately below the substance “Isocyanates”, the following substance:

<p>Lead and its compounds in controlled EEE</p>	<p>Controlled EEE containing lead not exceeding 0.1% maximum concentration value by weight of homogeneous material in controlled EEE;</p> <p>Lead in glass of cathode ray tube;</p> <p>Lead, not exceeding 0.2% by weight, in glass of fluorescent tube;</p> <p>Lead, not exceeding 0.35% by weight, as an alloying element in steel for machining purposes or galvanised steel;</p> <p>Lead, not exceeding 0.4% by weight, as an alloying element in aluminium;</p> <p>Lead, not exceeding 4% by weight, in copper alloy;</p> <p>Lead in high melting temperature type solder (that is, lead-based alloy containing 85% by weight or more lead);</p> <p>Electrical and electronic component containing lead in —</p> <p>(a) glass or ceramic (other than dielectric ceramic in capacitor); or</p> <p>(b) glass or ceramic matrix compound;</p> <p>Lead in dielectric ceramic in capacitor for rated voltage of 125 V AC, 250 V DC or higher;</p> <p>Lead in bearing shell or bush for refrigerant-containing compressor for heating, ventilation, air conditioning or refrigeration application;</p>
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	<p>Lead in white glass for optical application;</p> <p>Lead in filter glass or glass used for reflectance standards;</p> <p>Lead in printing ink for the application of enamel on glass;</p> <p>Lead in solder for —</p> <p>(a) completing viable electrical connection between semiconductor die and carrier within integrated circuit flip chip package;</p> <p>(b) soldering to machined-through hole discoidal or planar array ceramic multilayer capacitor; or</p> <p>(c) soldering thin copper wire (with diameter not exceeding 100 µm) in power transformer;</p> <p>Lead in soldering materials in mercury-free flat fluorescent lamp;</p> <p>Lead oxide in surface conduction electron emitter display used in structural element;</p> <p>Lead bound in crystal glass;</p> <p>Lead in cermet-based trimmer potentiometer element;</p> <p>Lead in plating layer of high-voltage diode on base of zinc borate glass body.</p>
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